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Chandrayaan-1 X-ray spectrometer (C1XS) – Instrument design and technical details

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1	Chandrayaan-1 X-ray Spectrometer (C1XS) – Instrument Design & Technical Details
2	
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20	
21	
22	Abstract
23	
24	The UK-built Chandrayaan-1 X-Ray Spectrometer (C1XS) is flying as an ESA instrument on
25	India's Chandrayaan-1 mission to the Moon. The Chandrayaan-1 mission launched on the 22 nd

26	October 2008 and entered a 100 km polar lunar orbit on the 12 th November 2008. C1XS builds
27	on experience gained with the earlier D-CIXS instrument on SMART-1, but will be a
28	technically much more capable instrument. Here we describe the instrument design.
29	
30	Keywords: Detectors; SCD; Swept Charge Device; X-ray Fluorescence; Moon
31	
32	
33	1. Introduction
34	
35	The Chandrayaan-1 X-ray fluorescence Spectrometer (C1XS) is based upon the successful
36	technology demonstration D-CIXS instrument that was flown on the ESA SMART-1 mission
37	(Grande et al., 2003; 2007). The restructured C1XS instrument design had to take into
38	account the different thermal environment, the shorter Earth-Moon transit time, and the lower
39	lunar orbit of the Chandrayaan-1 mission compared to the SMART-1 mission. The scientific
40	objectives of this instrument, which include mapping the abundances of the major rock-
41	forming elements (principally Mg, Al, Si, Ti, Ca and Fe) in the lunar crust are discussed by
42	Crawford et al., (in press). Here we describe the instrument design and technical challenges
43	presented by the C1XS instrument which uses innovative swept charge device (SCD) detector
44	technology (Grande et al., 2003; Holland et al., 2004; Smith et al., 2007).
45	
46	The C1XS instrument, like its predecessor, will be accompanied by a X-ray Solar Monitor
47	(XSM) instrument.
48	
49	2. XSM Instrument

51	The XSM is very similar to the instrument for SMART-1 described in Huovelin et al. (2002)
52	and Alha et al. (2008). It consists of an aluminium enclosure containing a high purity silicon
53	PIN (Positive Intrinsic Negative) diode detector, a Peltier cooler, front end electronics, and a
54	shutter mechanism (Fig.1). The signal processing card is fitted inside the C1XS electronics
55	module; the data produced is read by the C1XS processor, assembled into 512 bin spectra and
56	transmitted to the spacecraft solid state recorder (SSR).
57	
58	The PIN diode is formed on a square chip and has a circular active area. Three concentric
59	guard rings surround the active detection area. To reduce the count rate an aperture stop made
60	from a golden annular structure is centred on the surface of the detector. The detector window
61	consists of a 13 μm beryllium foil coated with 0.25 μm polyimide and 90 nm aluminium. A
62	collection of the XSM performance values are shown in Table 1.
63	2
64	The main differences from the SMART-1 XSM are: (1) improvement in the noise performance
65	implying better spectral resolution as well as a lower energy cut-off, and (2) a smaller aperture
66	resulting in decreased sensitivity to allow measurements of spectral signature of very strong
67	flares.
68	
69	3. C1XS Instrument
70	
71	2 and Fig. 3) weighs 5.56 kg and has physical dimensions of approximately 250 mm wide by
72	150 mm tall by 190 mm deep (with the door closed). It is functionally and thermally divided
72 73	150 mm tall by 190 mm deep (with the door closed). It is functionally and thermally divided into two parts. The larger section is the electronics module. This module contains the

75 and five circuit boards. The circuit boards are arranged side-to-side, and are held in place with

76	wedge-locking card guides. The electronics enclosure is a thick-walled (4 mm) aluminium
77	box, which acts as the instrument's primary structure. The second section is the detector
78	module. This houses the swept charge device (SCD) X-ray detectors together with their
79	associated drive electronics, radiation shielding and cooling interface. It is supported by the
80	electronics module in a cantilever fashion.
81	
82	The instrument (Fig. 1) weighs 5.5 kg and the instrument is bolted down to the Chandrayaan-1
83	spacecraft deck using 4 screws to provide a good thermal interface between the instrument and
84	the spacecraft panel/radiator. Table 2 gives a list of requirements together with the actual
85	values measured during the C1XS calibration and test.
86	5
87	3.1 Overview of C1XS Instrument Operation
88	2
89	C1XS uses a form of Charge Coupled Device (CCD) developed by e2v specifically to detect
90	X-rays. When an X-ray in the 0.5 to 20 keV energy range arrives at the device it deposits a
91	charge which is proportional to the energy of the X-ray. This charge is read by the C1XS and
92	converted to a digital amplitude value. (Detail of how the detectors operate is provided in
02	
93	more detail in section 3.3.) The digital value is compared with a software configured threshold,
93 94	more detail in section 3.3.) The digital value is compared with a software configured threshold, any event above the threshold is considered to be a valid X-ray event (see section 3.4). The
93 94 95	more detail in section 3.3.) The digital value is compared with a software configured threshold, any event above the threshold is considered to be a valid X-ray event (see section 3.4). The validated event is either assembled into a data packet or used by the C1XS data processing
93 94 95 96	more detail in section 3.3.) The digital value is compared with a software configured threshold, any event above the threshold is considered to be a valid X-ray event (see section 3.4). The validated event is either assembled into a data packet or used by the C1XS data processing system to create a spectrum for each SCD. The generated spectrum is made up of 512 energy
93 94 95 96 97	more detail in section 3.3.) The digital value is compared with a software configured threshold, any event above the threshold is considered to be a valid X-ray event (see section 3.4). The validated event is either assembled into a data packet or used by the C1XS data processing system to create a spectrum for each SCD. The generated spectrum is made up of 512 energy bins, for each event the C1XS software calculates within which energy bin the event would fall
93 94 95 96 97 98	more detail in section 3.3.) The digital value is compared with a software configured threshold, any event above the threshold is considered to be a valid X-ray event (see section 3.4). The validated event is either assembled into a data packet or used by the C1XS data processing system to create a spectrum for each SCD. The generated spectrum is made up of 512 energy bins, for each event the C1XS software calculates within which energy bin the event would fall and increments that bin's number of counts. Every 8 seconds each SCD spectrum is assembled
93 94 95 96 97 98 99	more detail in section 3.3.) The digital value is compared with a software configured threshold, any event above the threshold is considered to be a valid X-ray event (see section 3.4). The validated event is either assembled into a data packet or used by the C1XS data processing system to create a spectrum for each SCD. The generated spectrum is made up of 512 energy bins, for each event the C1XS software calculates within which energy bin the event would fall and increments that bin's number of counts. Every 8 seconds each SCD spectrum is assembled into a data packet and the bin counters are reset to zero.

101 **3.2 Detector Module**

102

103	The detector module is mounted on the front of the electronics module via a 12 mm thick
104	GFRP (glass fibre reinforced polymer) spacer. The heads of the bolts used to hold the two parts
105	together are also insulated from the detector module. The GFRP spacer is covered with
106	stainless steel foil, designed to provide electromagnetic shielding without adding a significant
107	thermal connection. The void between the 2 modules is filled with a 10 layer multi-layer
108	insulation (MLI) blanket to reduce the radiative coupling between the hot video processing
109	electronics and the back of the cold detectors. The electrical interface between the two parts is
110	via a flexi-rigid circuit board which has been designed to minimise heat transfer (Fig. 3).
111	5
112	The SCD clock driver PCB (printed circuit board) is fixed to the rear of the detector module
113	and contains the power drive stages for the SCD clocks and the interface connectors for the
114	SCD modules. There are 3 SCD modules, each with an interface PCB. Each module contains
115	two strips of SCDs with 4 SCDs in each strip. The SCD strips are mounted on a 3 mm copper
116	and a 6 mm tantalum heatsink, which is thermally isolated from the rest of the module. The
117	tantalum is included for proton shielding but also provides additional thermal mass. The
118	copper protrudes from the bottom of each SCD module to allow the external radiator to be
119	connected to the instrument via a heatpipe (Fig. 3).
120	

To constrain the detector field of view, a CNC (computerised numeric control) machined
copper collimator (Fig. 4) is mounted above each detector. This provides an angular acceptance
of 28° (i.e. +/- 14°) from the 100 km orbit of Chandrayaan-1, the C1XS field of view being
equivalent to a 50 km square (full width) on the surface of the Moon. The dimensions of the
machined holes in the copper are 1.5 mm square with a wall thickness of 0.15 mm. The signal

126 loss due to the copper walls is just 17 %. This is a superior performance to the D-CIXS

127 collimators which lost \sim 30%. To allow the walls to be made this thin the maximum machining

128 depth is 1 mm. Therefore, a complete collimator is composed of six machined copper sheets

129 stacked up to give the necessary opening angle. As part of the CNC process extra holes are

130 machined to allow the individual sheets to be accurately aligned and fixed together to ensure

131 correct construction of each collimator stack.

132

133 SCDs are not just sensitive to X-rays; light and low energy electrons can also mimic an X-ray 134 signal. A 0.2 μ m aluminium foil supported on 0.2 μ m polyimide is therefore mounted to the 135 top and bottom layers of the collimator stack. The reason for having two thin foils rather than 136 one thicker foil is to eliminate possible problems with pin-hole defects in the foils. It is very 137 unlikely that an individual column would have a pin-hole present in both of the foils and even 138 less likely that the two holes would line up to provide a light path through to a detector. One of 139 the internal collimator layers has additional vent paths included to ensure that the trapped 140 volume of air does not cause the aluminium foil to rupture during the decompression 141 experienced during the launch. The vent paths are designed to reduce the possibility of light 142 entering one collimator getting to another if the external foil is ruptured. Unlike D-CIXS where 143 seven of the detectors were mounted behind a magnesium foil collimator assembly (Grande et 144 al., 2003), the new C1XS instrument only employs aluminium foils. A photograph of a partly 145 built collimator stack and a schematic of the collimator assembly are shown in Figure 4.

146

147 The entire detector module is protected by a 5 mm thick aluminium door. This door is actuated 148 with a stepper motor, using a rotary potentiometer for control. DCIXS used microswitches at 149 each end of the door's travel and so the precise door position was never known. The 150 potentiometer fitted to C1XS will allow the door position to be measured at all times. The

door is secured for launch using a one-shot HOP wax actuator and contains 24 ⁵⁵Fe sources for
calibrating the detectors when closed.

153

Each ⁵⁵Fe calibration source consists of a 220 kBq nickel coated electro-deposited source on an
aluminium carrier which is mounted behind a 5 µm titanium foil. The titanium is used to
produce an additional pair of calibration lines so the source gives a total of four X-ray energies;
4.510, 4.931, 5.895 and 6.4942 keV corresponding to the K-alpha and K-beta lines of Ti and
Mn, respectively.

so that the measurements from the lunar surface are not 'contaminated' with the X-rays emitted by the calibration sources. Due to the titanium foil and the collimation the count rate seen by each detector is approximately 200 counts per second. At the beginning of the mission 10 minutes of calibration data will be taken once per day to monitor the SCD degradation, the time may be lengthened as the mission progresses due to the source half life (2.7 years).

- 166
- 167 **3.3 Swept Charge Devices and Drivers**

168

A schematic of the SCD internal structure is given in Figure 4 and the device characteristics, specified by the supplier, are given in Table 3. The device has 3 clock lines which are arranged in a design that, upon clocking, will 'sweep' any charge towards a low capacitance sense amplifier located in one corner of the detector (the bottom left-hand corner as shown in Figure 5). The device is clocked continuously at 87 kHz using a 10 V drive level, the clock waveforms produced by the field-programmable gate array (FPGA) are non-overlapping and the design relies on the SCD internal capacitance and a series resistor to ensure that sufficient

176 overlap is present to give correct charge transfer. Switching the clocks simultaneously

177 substantially reduces clock noise feedthrough leading to a significant improvement in detector

178 performance. Using a lower clock frequency than that specified by the manufacturer increases

179 the theoretical dark current by approximately 2 electrons per sample.

180

181 The design of the sense amplifier is based upon that used in traditional CCD technology,

182 consisting of a very low capacitance sense amplifier and reset transistor, and operates in

183 exactly the same way as in a conventional CCD. The SCD supply voltages are listed in Table

184 4. All 24 SCD use the same supply and clock voltages to minimise the complexity of the drive

electronics and because the 24 SCD are contained on 6 substrates each of which has common

186 bias voltage and clock connections. As part of the characterisation work done by Brunel

187 University, the SCD drive voltages and biases were investigated in detail and it was found that

188 all the flight candidate devices could perform well under a single set of optimised voltages.

189 Figure 6 shows one parameter investigated in the study, the variation in noise as a function of

190 output drain voltage. All the devices used in the final flight instrument were characterised

191 using the specified optimal voltages and were the 'best' modules chosen for those operating

192 conditions.

193

The four SCD bias voltages and logic-level clocks are generated on the video-digital PCB and are connected to the SCD via the video-analogue card. The clock driver board is mounted directly on the detector assembly module and uses flexi-rigid circuits to connect to the analogue card. Different flexible circuits are used to separate the drive waveforms/supplies to the detectors from the SCD video outputs to minimise interference.

200 The clock driver board carries the power driver ICs (integrated circuits) for the clocks, and the

201 connectors which allow the SCD modules to be plugged in once the rest of the instrument is

202 assembled. The PCB on the back of the SCD module holds the SCD supply filter components

- 203 to provide decoupling as close to the device as possible.
- 204
- 205 The substrate and output gate voltages for the SCDs are each generated using a DAC08 digital

206 to analogue converter followed by a power drive stage. The remaining two voltages come

207 from a switched-mode power supply (SMPS) which is synchronised to the SCD readout

208 system. The output of the SMPS is filtered and then the actual output voltage selected using

- 209 linear voltage regulators. Control for these voltages comes from the video processing boards. nus
- 210
- 211 **3.4 SCD Video Processing**
- 212

213 The signals from each SCD flow through 3 main processing blocks: video amplification and 214 sampling, digitisation, and event recognition (Fig. 7). As the output from an SCD is similar to a 215 conventional CCD, a correlated double sampling (CDS) circuit is used to extract the wanted 216 signal. The CDS circuit takes two samples from the SCD for each pixel, the reset level and 217 then the X-ray event signal, and calculates the difference between the two values. This voltage 218 is then fed, via a summing junction, to an analogue to digital converter (ADC) which gives a 219 14 bit number equivalent to the X-ray event energy. The summing junction allows the position 220 of the zero voltage signal to be placed anywhere on the ADC range, in practice this position is 221 chosen to be at a value of 350 so that when the temperature changes, both positive and negative 222 drift of the zero position can be detected. The instrument uses a total of 24 SCD, each 223 requiring its own CDS circuit, so an integrated solution is required to allow all the parts to be 224 fitted on the Eurocard sized PCB. A Burr Brown 3 channel CDS integrated circuit was chosen

225	as the main processing element. Four of these devices plus support logic were built into a
226	module produced by 3D Plus and supplied by CESR with the support of CNES (Fig. 8). As the
227	CDS parts are designed for optical CCD signals a pre-amplifier stage is used immediately
228	before the CDS block to give sufficient resolution. The amplifiers have an enable input which
229	is used to blank out the SCD reset pulse.
230	
231	Each 3D Plus module, containing the CDS, is controlled using an Actel RTAX250 FPGA.
232	This device provides the sequencing of detector readout and digitisation. It also is used to
233	select valid X-ray events from the detector video streams. The event-selection logic stores
234	samples from each detector and processes them according to a programmable criterion using
235	two thresholds. The thresholds are selected such that X-ray events less than $\sim 800 \text{ eV}$ are
236	rejected by the system (threshold one). Threshold two is used to reject events where a single X-
237	ray is spread over two or more pixels. The two event selection modes used by C1XS (Fig.9)
238	are:
239	
240	1. 'Multi-pixel' mode – on pixel B greater than threshold 1, up to 5 consecutive pixels
241	(hatched area) are stored in the FIFO.
242	GOV
243	2. 'Single pixel' mode – on pixel B greater than threshold 1, and both A and C less than
244	threshold 2, store pixel B (crosshatched area).
245	
246	In addition, on demand from the instrument processor, the FPGA can store one raw data
247	sample from each detector without reference to the programmed thresholds which gives an
248	event value somewhere within the ADC range. As the read-out rate for each detector is ~ 87
249	kHz and the highest expected X-ray event rate is 900 events per second (X10 flare conditions)

250	the probability that the value read is an X-ray is 0.01. Therefore a non-thresholded event is
251	most likely to be a measure of the system noise with respect to a zero energy value. The
252	instrument software integrates these data to give a value of the zero energy position and adjusts
253	the FPGA event thresholds accordingly. In addition these data are added to the telemetry
254	packets transmitted from the instrument and are used to keep a check on the front-end analogue
255	offsets which determine the zero-energy position in the accumulated X-ray spectra. All the
256	validated X-ray events are stored in a FIFO which is read by the C1XS micro-controller 32
257	times per second. It is impossible to distinguish FPGA events generated by genuine X-rays
258	from events related to the penetrating particle background. However, by using the measured
259	spectra from very quiet solar conditions (<b1 a<="" can="" determine="" flux="" goes="" level),="" td="" we="" x-ray=""></b1>
260	background spectrum which can be used to remove the cosmic ray induced X-ray signal.
261	
262	3.5 Data Processing System
263	
264	Figure 10 shows a block view of the C1XS data processing system. An RTX2010
265	microcontroller is used for the main instrument processing. It is located on one of the plug in
266	PCBs together with 256 kBytes RAM, 128 kBytes fuse linked PROM (programmable read
267	only memory) and 256 kBytes EEPROM (electrically erasable read only memory). The
268	software is written in a mixture of assembler and C code and has two main parts; the first is an
269	emergency level system that allows basic communication with the instrument, the ability to
269 270	emergency level system that allows basic communication with the instrument, the ability to read and modify RAM, start execution at a specific memory location and to boot from
269 270 271	emergency level system that allows basic communication with the instrument, the ability to read and modify RAM, start execution at a specific memory location and to boot from EEPROM having validated the integrity of the software to be run. The second part is the main
269 270 271 272	emergency level system that allows basic communication with the instrument, the ability to read and modify RAM, start execution at a specific memory location and to boot from EEPROM having validated the integrity of the software to be run. The second part is the main instrument software which is run after the C run-time system has initialised. The instrument
 269 270 271 272 273 	emergency level system that allows basic communication with the instrument, the ability to read and modify RAM, start execution at a specific memory location and to boot from EEPROM having validated the integrity of the software to be run. The second part is the main instrument software which is run after the C run-time system has initialised. The instrument boots into 'Standby' mode which allows full commanding via the databus and produces

275	
276	• C1XS Door open/close
277	• Collect and transmit instrument operating parameters
278	• Synchronise internal clock to spacecraft clock
279	• Accept commands
280	
281	Instrument 'Operating' mode is entered via a telecommand and, on starting this mode, the
282	software checks that certain temperatures have not been exceeded; powers on the video
283	processing circuits and the SCD power supplies; loads various parameters into the integrated
284	circuits and starts the XSM state machine. The state machine is used to control the operation
285	of the XSM detector cooler, data collection and protective shutter. Some flexibility is built into
286	operating mode which allows each of the two C1XS 3D Plus modules to be run on their own
287	both with and without the XSM.
288	
289	In the normal operating mode the C1XS telemetry data format depends on the X-ray count rate,
290	one of three possible science formats will be chosen. If the total X-ray rate for all 24 detectors
291	is <320 events/sec then the FPGA uses the first event selection mode (multi-pixel data).
292	Although this FPGA mode allows up to 5 pixels to be selected the instrument only uses three
293	consecutive readout events – the actual event plus the before and after events (i.e. A, B and C
294	in Figure 9). The science telemetry packet produced contains the event time and the 3 energy
295	values and is called '3-pixel mode'. Above 320 events/sec the FPGA uses its second mode
296	(single pixel) so that only one pixel of data is used (event B in Figure 9). Two telemetry
297	formats use the single pixel mode, the first is a time tagged mode where the telemetry packet
298	contains the event time and the energy value and the second is a spectral one which is used
299	when the count rate exceeds 800 events/sec. The spectral format is an optimised 512 channel

300	spectrum with variable bin widths to maximise the scientific return of the instrument. Spectra
301	are generated every 8 seconds, an unprocessed spectrum generated from the on-board
302	calibration source is shown in Figure 11. In normal operations the instrument will
303	autonomously select the data mode itself by checking the instrument data rate every second.
304	Alternatively, the instrument can be commanded into one of the three C1XS science modes
305	(time tagged – 3 pixel mode, time tagged – single pixel mode or high resolution low count
306	spectral mode). For compatibility, we can also use one of the three earlier D-CIXS science
307	modes (simple time tagged mode, low count spectral mode or compressed low count spectral
308	mode).
309	
310	The electronics monitors the SCD temperatures, using a thermistor mounted on the rear of the
311	SCD copper heatsink, and switches to a low power mode ('Resting') if they get too hot (\sim
312	-5°C). This mode allows the detectors to cool down and data collection is re-enabled once the
313	temperature has reduced sufficiently (to $\sim -9^{\circ}$ C).
314	Ó
315	Operating mode functions include:
316	• Monitor box and video processor temperatures, switch to standby if limit
317	exceeded
318	• Monitor SCD temperatures, switch to low power mode (Resting) if limit
319	exceeded
320	• Control and monitor XSM
321	• Monitor SCD X-ray event rate and generate appropriate science data packet
322	• Collect and transmit instrument and SCD operating parameters
323	• Synchronise internal clock to spacecraft clock
324	 Accept commands

325	
326	Resting mode functions:
327	• Monitor box and video processor temperatures, switch to standby if limit
328	exceeded
329	• Monitor SCD temperatures, switch to operating mode if SCD are cool enough
330	• Collect and transmit instrument operating parameters
331	• Synchronise internal clock to spacecraft clock
332	• Accept commands
333	
334	3.6 Spacecraft Interface
335	5
336	The C1XS instrument uses a CAN bus to communicate with the rest of the spacecraft. The
337	CAN protocol circuits were designed and supplied by Swedish Space Corporation using Actel
338	RT54SX32 devices. The system implemented uses two CAN busses, one which is in use and
339	the other as a hot standby. The protocol chip automatically selects the active bus depending on
340	the presence of a 'use this bus' message which is repeated every second and, if no message is
341	received, then the device automatically uses the other bus. The spacecraft time is also sent
342	using a specific CAN message on the bus to synchronise the C1XS instrument time to the
343	spacecraft time.
344	
345	A second Actel on the interface board is used to provide control signals for the multiplexers
346	and analogue to digital converter and to latch the converter result. This device is also used to
347	control the door latch drive and the door stepper motor.

349 The door stepper motor drive waveforms are generated under software control, this allows the 350 actual door movement to be fine tuned to give a smooth opening/closing action and means that 351 the door drive can be adjusted, if required, as the mission progresses. The door latch drive 352 takes power directly from the spacecraft side of the C1XS power supply as the mechanism 353 requires 28 V. To maintain isolation between the spacecraft and instrument grounds a pulse 354 transformer is used to drive the power switching transistors, this has the additional advantage 355 that a short circuit failure on the C1XS side of the transformer will not permanently activate 356 Scrib the HOP drive.

357

358 **3.7 Power Supplies**

359

360 The power input to the main switched mode power supply (SMPS) is routed via a pulse

361 activated power relay. The 30 W SMPS and accompanying filter module is used to generate

362 the main 5 V and ± 12 V supplies. A RAL-designed PCB then contains the post SMPS filters

363 and two additional supplies: a 1.5V rail for the XSM peltier cooler and a - 5 V rail for the video

364 amplifiers. All these items are assembled onto the -X face of the C1XS box prior to the

365 assembly of the rest of the electronics module, when the backplane is fitted.

366

4. Calibration 367

368

369 Figure 9 also illustrates the predicted performance of the D-CIXS instrument after 15 months 370 of radiation damage during transit to the Moon. The performance is greatly degraded by 371 radiation damage from the trapped protons in Earth's radiation belts encountered on the long 372 journey time to the Moon. In contrast, Chandrayaan-1 will arrive at its destination lunar orbit 373 within one week, resulting in much greater spectral performance at the start of the mission

(Smith et al., 2007). An equally significant lesson we learned from D-CIXS is the requirement

375	for greater detail <i>in press</i>). The typical measured instrument readout noise is 6-7 electrons rms
376	
377	Figure 12 also illustrates the performance of the D-CIXS instrument after 15 months of
378	radiation damage during transit to the Moon for an equivalent input spectrum. The
379	performance is greatly degraded by radiation damage from the trapped protons in Earth's
380	radiation belts encountered on the long journey time to the Moon. In contrast, Chandrayaan-1
381	has arrived at its destination lunar orbit within three weeks, resulting in much greater spectral
382	performance at the start of the mission (Smith et al., 2007). An equally significant lesson we
383	learned from D-CIXS is the requirement for greater detail in the spectrum at low energies. To
384	address this issue, C1XS has four times the number of channels over the energy range 0 to 4.
385	
386	Conclusions
387	
388	5. Conclusions
389	

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374

388 5. Conclusions

389

390 The C1XS instrument builds upon the experience gained during the build and lessons learnt 391 during the operation of the D-CIXS instrument (Grande et al., 2007; Swinyard et al., in press). 392 Table 2 details the design requirements based on the science case outlined in Crawford et al. 393 (in press) and specifications from the Indian Space Research Organisation together with the 394 actual values measured during the instrument test. The key requirement for a good scientific 395 return from the instrument is the ability to discriminate between the aluminium and magnesium 396 energies (240 eV) hence the better than 200 eV spectral resolution requirement. The C1XS 397 instrument during calibration achieved a resolution of 85 eV and data from the initial lunar 398 commissioning work shows that radiation damage during the Earth-Moon transit is minimal (<

30 eV) so the worst case beginning of life resolution is 115 eV, almost a factor of two betterthan the requirement.

401 The greatest improvement to the build process was the use of CNC to machine the collimator 402 structures. The complete set of collimators was made within one month and each was of 403 uniform thickness and quality - the D-CIXS parts took more than 6 months to make and 404 suffered from poor flatness and lack of uniformity. The disadvantage of the C1XS approach 405 was an increased collimator height (due to the larger hole size necessary to ensure that the loss 406 due to the thicker walls was minimised). However, the C1XS collimators out-perform the D-407 CIXS ones because the thinner walls and larger holes lead to a factor ~2 smaller loss of X-rays 408 to the walls.

409

410 During D-CIXS instrument operations it was found that the SCD temperature rose very quickly 411 as the spacecraft traversed the sunlit side of the Moon, typically the SCD temperature was -30 412 °C at the terminator crossing and the instrument went into 'resting' mode (SCD temperature of 413 $-9 \,^{\circ}$ C) near the equator. The thermal performance of the new instrument is expected to be 414 much better due to the significantly greater level of design work that has taken place to reduce 415 the overall instrument power and to more thoroughly isolate the SCD from the electronics 416 module. The provision of a dedicated cooling system for the SCD by Chandrayaan-1 itself 417 should help to ensure that the operating target temperature of -20 °C is maintained for greater 418 than 95 % of the orbital configurations.

419

The electronics design was improved in two ways. First, all the power supplies were changed
to a switched mode design. This reduces the overall power drawn by the full instrument
(helping to reduce the thermal load). Second, significantly more time was spent improving the
SCD drive circuits and amplifiers to improve the readout noise performance. This has resulted

- 424 in a readout noise figure of 6-7 electrons rms (*Kellett et al., forthcoming*). This is about a factor
- 425 of 2 better than the readout noise performance of D-CIXS.
- 426

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487 **Table Captions**

488

489
 Table 1. XSM Parameters

490 Table 2. C1XS Requirements and achieved values.

491 Table 3. Swept Charge Device Design Specification.

- 492 Table 4. SCD Voltages.
- 493

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494	Figure Captions
495	
496	Figure 1. View of the XSM instrument
497	
498	Figure 2. View of the C1XS instrument on its vibration fixture. The door covering the SCD
499	collimators can be identified by the radioactive warning symbol. The door HOP actuator is
500	mounted vertically and the motor horizontally. The two connectors are the CAN bus and the
501	XSM interfaces.
502	
503	Figure 3. Schematic view of the C1XS instrument with one side of the instrument cut away.
504	5
505	Figure 4. Photograph of a partly built collimator stack. Schematic of the collimator assembly.
506	
507	Figure 5. A schematic of the SCD internal structure. The electrodes are depicted by the dashed
508	lines, whilst the charge transport channels are indicated by solid lines. The charge is swept
509	towards the central channels and down to the output amplifier (bottom left corner) by the
510	action of the clock signals.
511	GOV
512	Figure 6. Variation in SCD readout noise (electrons) with Output Drain voltage.
513	
514	Figure 7. Block diagram showing the C1XS video processing system.
515	
516	Figure 8. Video-analogue PCB component side view showing the two 3Dplus signal
517	processors and associated amplifiers.
518	

519	Figure 9. C1XS X-ray 'single pixel' event selection – an X-ray event is selected when pixel B
520	is greater than threshold 1 and the pixels immediately before and after (A and C) are BOTH
521	below threshold 2. Multi-pixel event selection – Up to 5 pixels (crosshatched area) are selected
522	when pixel B is greater than threshold 1.
523	

524 **Figure 10.** C1XS data processing block diagram.

525

526 Figure 11. Unprocessed Spectral Packet Data generated with X-ray events from the on-board

527 calibration source. This shows the two 55Fe lines, the position of the titanium lines, the 'zero'

- 528 noise peak, the FPGA cut-off point and some 'split' events not removed by the FPGA event
- 529 detection.
- 530

531 Figure 12. An example RESIK spectrum from a flight SCD. The red histogram (C1XS) is a

spectrum combined from two measurements a Cu-Mg anode and a pure Al anode to give the

533 three peaks seen (Cu Lα: 0.92 keV, Mg Kα: 1.25 keV, Al Kα: 1.49 keV). The blue spectrum is

a D-CIXS equivalent low count spectrum after 15 months radiation dose. Note that the red

spectrum has x4 channels to maximise the scientific return of C1XS.

XCC

536 **Table Captions**

537

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543 <u>Tables</u>

Nominal energy range	1.2–20.0 keV
Energy resolution(BOF)	200eVat 5.9 keV
Number of spectral channels	512
FOV(circular) Diameter	104°
On-axis geometric area	$0:001 \text{ cm}^2$

544 **Table 1**

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Parameter	Requirement	Achieved
Supply voltage	28 to 42 V	20 to 45 V
Power	<10W (Standby)	6.3 W (Standby)
	<30W (Operating)	25.5 W (Operating)
Temperature range		
Electronics	-50 to +80 (off)	As requirement
	-20 to +40 (operating)	
Detector module	-50 to +80 (off)	
	-40 to +0 (operating)	G
Mass	5.8 kg	5.56 kg
Dimensions (door closed)		
width (Y axis)	300 mm	248 mm
height (Z axis)	200 mm	151 mm
depth (X axis)	260 mm	190 mm
Energy Range	1 to 10keV.	0.8 to 20 keV
Field of view	<15 degrees (FWHM)	14 degrees (FWHM)
CC ^C	<30 degrees (full angle)	28 degrees (full angle).
Spectral resolution	<200 eV at 1.25 keV.	85 eV
Readout frequency	not specified	87,381 kHz
Data volume (average)	57 Mbits/orbit	36 Mbits/orbit

Table 2.

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10 x 10 mm	549				
30,000 counts/sec	550				
3 (typ.) to 5 (max.) electrons rms.	551				
(with 100KHz Correlated Double Sa	ampling)552				
140eV at Mn K _α	553				
>30% at 280eV	554				
>30% at 10keV	555				
-15°C	556				
Table 3.					
	10 x 10 mm 30,000 counts/sec 3 (typ.) to 5 (max.) electrons rms. (with 100KHz Correlated Double Sa 140eV at Mn K _α >30% at 280eV >30% at 10keV -15°C				

Table 3.

5	5	0
\mathcal{I}	\mathcal{I}	/

Substrate voltage	9 V
Output Gate voltage	3 V
Reset Drain voltage	17 V
Output Drain voltage	30 V

Table 4.

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